



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Morrison, et al.
Serial No.: 10/034827
Filed: 01/03/2002
Docket: TI-31373
For:

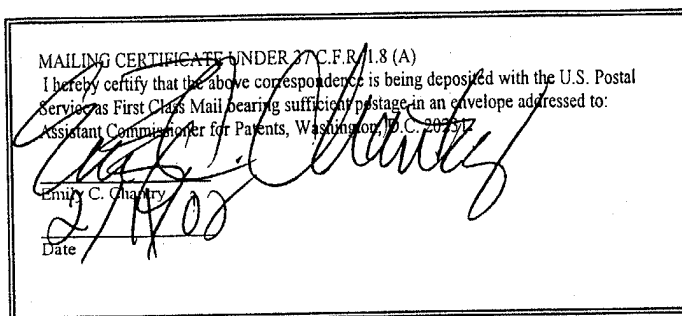
**CHIP-SCALE PACKAGES STACKED ON FOLDED
INTERCONNECTOR FOR VERTICAL ASSEMBLY ON SUBSTRATES.**

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OCT 18 2001
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REQUEST FOR CORRECTED FILING DATE

February 11, 2002

Assistant Commissioner
for Patents
Washington, D.C. 20231



Sir:

Applicant received a postcard indicating a filing date of January 3, 2002 for the above referenced Application.

However, the Mailing Certificate confirms that the Application was deposited with the U.S. Postal Service Express Mail (Label No. EV051432549US) on December 26, 2001.

A Declaration by Emily Chantry is enclosed to further corroborate mailing by Express Mail on December 26, 2001.

Applicant requests that the official filing date be corrected to **December 26, 2001** to reflect the date of mailing.

Respectfully Submitted,

Gary C. Honeycutt
Gary C. Honeycutt
Reg. No. 20,250
Attorney for Applicant

Godwin Gruber, P.C.
Renaissance Tower
1201 Elm Street, Ste. 1700
Dallas, Texas 75270
(214) 939-8651

G O D W I N R U B E R

GARY C. HONEYCUTT
Direct Dial: 972.331.1301
ghoneycutt@godwingrubber.com



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February 11, 2002

Attorneys
A Professional Corporation
Renaissance Tower
1201 Elm Street, Suite 1700
Dallas, Texas 75270
214.939.4400
214.760.7332 Fax

godwingrubber.com

VIA FIRST CLASS MAIL

Assistant Commissioner for Patents
Washington, D.C. 20231

Re: Patent Application For
**CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR
FOR VERTICAL ASSEMBLY ON SUBSTRATES**
Owner: Texas Instruments Incorporated
Serial No.: 10/034827
Attorney Docket No. TI-31373
Our File: 50000.2166

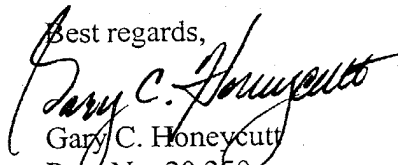
Dear Sir:

Enclosed for filing please find the following items relating to the above-identified application:

- (1) Request for Corrected Filing Date; and
- (2) Postcards.

Please file the application and return the date-stamped postcard to the corresponding addresses as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Best regards,


Gary C. Honeycutt
Reg. No. 20,250

GCH/ecc

Encls.

cc: Larry Bassuk, Texas Instruments Incorporated



February 11, 2002

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RE: Patent Application for:
CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR FOR VERTICAL ASSEMBLY ON SUBSTRATES
TI's File No.: TI-31373
Our File No.: 50000.2166

Enclosed with this postcard, please find the following:

1. Firm Cover Letter;
2. Request for Corrected Filing Date; and
3. Postcard.

Please date stamp this postcard to indicate that the above materials have been received and return to our office at the address on the back of this postcard.

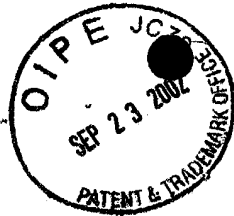
Thank You

VIA FIRST CLASS MAIL

In The "Received" stamp of the Patent and Trademark Office imprinted hereon acknowledges the filing of:

<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> AMENDMENT
<input type="checkbox"/> DECLARATION	<input type="checkbox"/> EOT
<input type="checkbox"/> ASSIGNMENT	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> APPEAL
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE
<input type="checkbox"/> CONTINUATION APP'N	<input checked="" type="checkbox"/> REPLY BRIEF (IN TRIPLICATE)
<input type="checkbox"/> DIVISIONAL APP'N	<input type="checkbox"/> Request for Corrected Filing Date

NAME OF INVENTOR(S): <i>Morrison et al.</i>	RECEIPT DATE & SERIAL NO.: Serial No.: <i>10/034827</i>
TITLE OF INVENTION: <i>Chip-Scale Packages Stacked On Folded Interconnector For Vertical Assembly On Substrates</i>	
TI FILE NO.: <i>TI-31373</i>	DEPOSIT ACCT. NO.: <i>20-0668</i>
EXPRESS MAIL RECEIPT NO.: MLD: <i>2/11/02</i> DUE: ATTY/SECY: <i>SCt/ccc</i>	<i>Via First Class Mail</i>



TI-31373

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Morrison, et al.
Serial No.: 10/034827
Filed: 01/03/2002
Docket: TI-31373
For:

**CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR
FOR VERTICAL ASSEMBLY ON SUBSTRATES.**

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DECLARATION

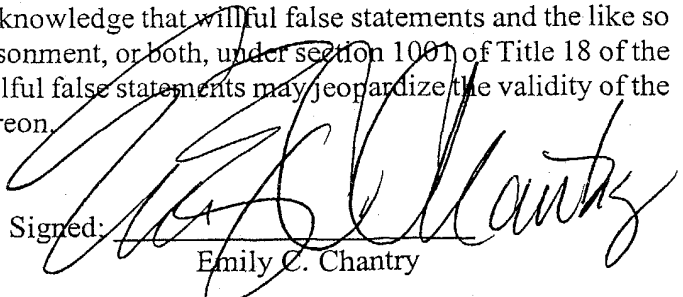
Emily Chantry of Plano, Texas hereby declares that she is a secretary at Godwin Gruber, P.C., and that she has more than 3 years experience in the preparation and mailing of papers to the United States Patent and Trademark Office (USPTO);

THAT in the performance of her duties as secretary of Gary C. Honeycutt, attorney of record, she prepared and mailed Application Serial Number 10/034,827 on December 26, 2001;

THAT said Application was placed in an Express Mail envelope, bearing proper postage, and then deposited with the U.S. Postal Service Express Mail Service, labeled with Mailing Label No. EV051432549US, on December 26, 2001; and

THAT Exhibit A, attached, is a true copy of the original Transmittal Form for said Application Serial Number 10/034,827 (Attorney Docket No. 31373) showing a duly executed Express Mailing Certificate, dated December 26, 2001, confirming that the Application is entitled to an Official Filing Date of December 26, 2001.

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Signed: 

Emily C. Chantry

Date: 2/14/02



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In The "Received" stamp of the Patent and Trademark Office imprinted hereon acknowledges the filing of:

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<input type="checkbox"/> ASSIGNMENT	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> APPEAL
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE
<input type="checkbox"/> CONTINUATION APP'N	<input type="checkbox"/> REPLY BRIEF (IN TRIPLICATE)
<input type="checkbox"/> DIVISIONAL APP'N	<input checked="" type="checkbox"/> Request for Corrected Filing Date

Stamp: OIPE JC125 FEB 27 2002 PATENT & TRADEMARK OFFICE

NAME OF INVENTOR(S): Morrison et al.		RECEIPT DATE & SERIAL NO.: Serial No.: 10/034827	
TITLE OF INVENTION: Chip-scale Packages Stacked On Solid Interconnectors for Vertical Assembly on Substrates			
FILE NO.: T1-31373	DEPOSIT ACCT. NO.: 20-0668		
EXPRESS MAIL RECEIPT NO.: MLD: 2/11/02			
DUE: 2/11/02			
ATTY/SECY: GCH/ecc		Via First Class Mail	

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MAR 13 2002
PATENT DEPT

KV

Receipt

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re the Application of

Morrison et al.

Docket No.: TI-31373

Serial No.: 10/034,827

Examiner: Mitchell, J.

Filed: 12/26/01

Art Unit: 2835

For: CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR
FOR VERTICAL ASSEMBLY ON SUBSTRATES

RECEIVED
OCT 18 2002
TECHNOLOGY CENTER 2800

REQUEST FOR CORRECTED FILING RECEIPT

September 9, 2002

Assistant Commissioner for Patents
Washington, DC 20231

Attn: Office of Initial Patent Examination's
Filing Receipt Corrections

Dear Sir:

MAILING CERTIFICATE	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.	
<i>Marianna Smith</i> Marianna Smith	<i>9-16-02</i> Date

The Filing Receipt dated 05/15/2002 erroneously indicates a filing date of 01/03/2002. A Request for Corrected Filing Date was mailed to the U.S. Patent and Trademark Office by Gary C. Honeycutt on February 11, 2002. A copy of that request along with the documentation is enclosed.

Issuance of a corrected Filing Receipt indicating the correct filing date of 12/26/01 is respectfully requested.

Please charge any necessary fees to Deposit Account No. 20-0668. An original and two copies of this sheet are enclosed.

Respectfully submitted,

Texas Instruments Incorporated
P.O. Box 655474, M/S 3999
Dallas, TX 75265
(972) 917-5653

Michael K. Skrehot
Michael K. Skrehot
Registration No. 36,682
Attorney for Applicants



UNITED STATES PATENT AND TRADEMARK OFFICE

MAY 28 2002
COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/034,827	01/03/2002	2835	1046	TI-31373	5	23	6

Gary C. Honeycutt
Godwin Grubber, P.C.
Suite 655
801 E. Campbell Rd.
Richardson, TX 75081



CONFIRMATION NO. 4496

FILING RECEIPT



OC00000008110937

Date Mailed: 05/15/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Gary P. Morrison, Garland, TX;
Darvin R. Edwards, Garland, TX;
Leslie Stark, Dallas, TX;

Domestic Priority data as claimed by applicant

THIS APPLN CLAIMS BENEFIT OF 60/258,525 12/28/2000

Foreign Applications

If Required, Foreign Filing License Granted 04/10/2002

Projected Publication Date: 08/22/2002

Non-Publication Request: No

Early Publication Request: No

Title

Chip-scale packages stacked on folded interconnector for vertical assembly on substrates

Preliminary Class

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